

# SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

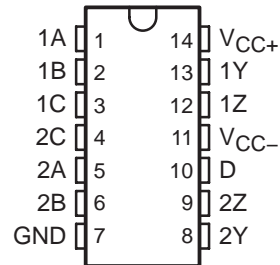
SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

- Improved Stability Over Supply Voltage and Temperature Ranges
- Constant-Current Outputs
- High Speed
- Standard Supply Voltages
- High Output Impedance
- High Common-Mode Output Voltage Range  
... -3 V to 10 V
- TTL-Input Compatibility
- Inhibitor Available for Driver Selection
- Glitch Free During Power Up/Power Down
- SN75112 and External Circuit Meets or Exceeds the Requirements of CCITT Recommendation V.35

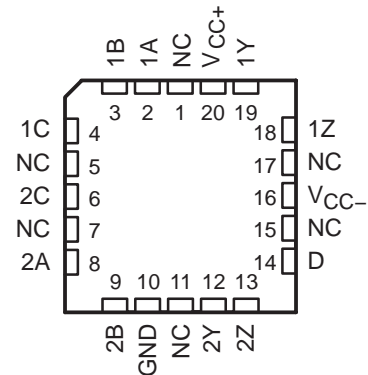
## description/ordering information

The SN55110A, SN75110A, and SN75112 dual line drivers have improved output current regulation with supply-voltage and temperature variations. In addition, the higher current of the SN75112 (27 mA) allows data to be transmitted over longer lines. These drivers offer optimum performance when used with the SN55107A, SN75107A, and SN75108A line receivers.

SN55110A ... J OR W PACKAGE  
SN75110A ... D, N, OR NS PACKAGE  
SN75112 ... D OR N PACKAGE  
(TOP VIEW)



SN55110A ... FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	SN75110AN	SN75110AN
			SN75112N	SN75112N
	SOIC (D)	Tube of 50	SN75110AD	SN75110A
		Reel of 2500	SN75110ADR	
		Tube of 50	SN75112D	SN75112
		Reel of 2500	SN75112DR	
SOP (NS)	Reel of 2000	SN75110ANSR	SN75110A	
-55°C to 125°C	CDIP (J)	Tube of 25	SN55110AJ	SN55110AJ
			SNJ55110AJ	SNJ55110AJ
	CFP (W)	Tube of 150	SNJ55110AW	SNJ55110AW
	LCCC (FK)	Tube of 55	SNJ55110AFK	SNJ55110AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated  
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

## description/ordering information (continued)

These drivers feature independent channels with common voltage supply and ground terminals. The significant difference between the three drivers is in the output-current specification. The driver circuits feature a constant output current that is switched to either of two output terminals by the appropriate logic levels at the input terminals. The output current can be switched off (inhibited) by low logic levels on the enable inputs. The output current nominally is 12 mA for the '110A devices and is 27 mA for the SN75112.

The enable/inhibit feature is provided so the circuits can be used in party-line or data-bus applications. A strobe or inhibitor (enable D), common to both drivers, is included for increased driver-logic versatility. The output current in the inhibited mode,  $I_{O(off)}$ , is specified so that minimum line loading is induced when the driver is used in a party-line system with other drivers. The output impedance of the driver in the inhibited mode is very high. The output impedance of a transistor is biased to cutoff.

The driver outputs have a common-mode voltage range of  $-3\text{ V}$  to  $10\text{ V}$ , allowing common-mode voltage on the line without affecting driver performance.

All inputs are diode clamped and are designed to satisfy TTL-system requirements. The inputs are tested at  $2\text{ V}$  for high-logic-level input conditions and  $0.8\text{ V}$  for low-logic-level input conditions. These tests ensure  $400\text{-mV}$  noise margin when interfaced with TTL Series 54/74 devices.

The SN55110A is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN75110A and SN75112 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE  
(each driver)

LOGIC INPUTS		ENABLE INPUTS		OUTPUTS†	
A	B	C	D	Y	Z
X	X	L	X	Off	Off
X	X	X	L	Off	Off
L	X	H	H	On	Off
X	L	H	H	On	Off
H	H	H	H	Off	On

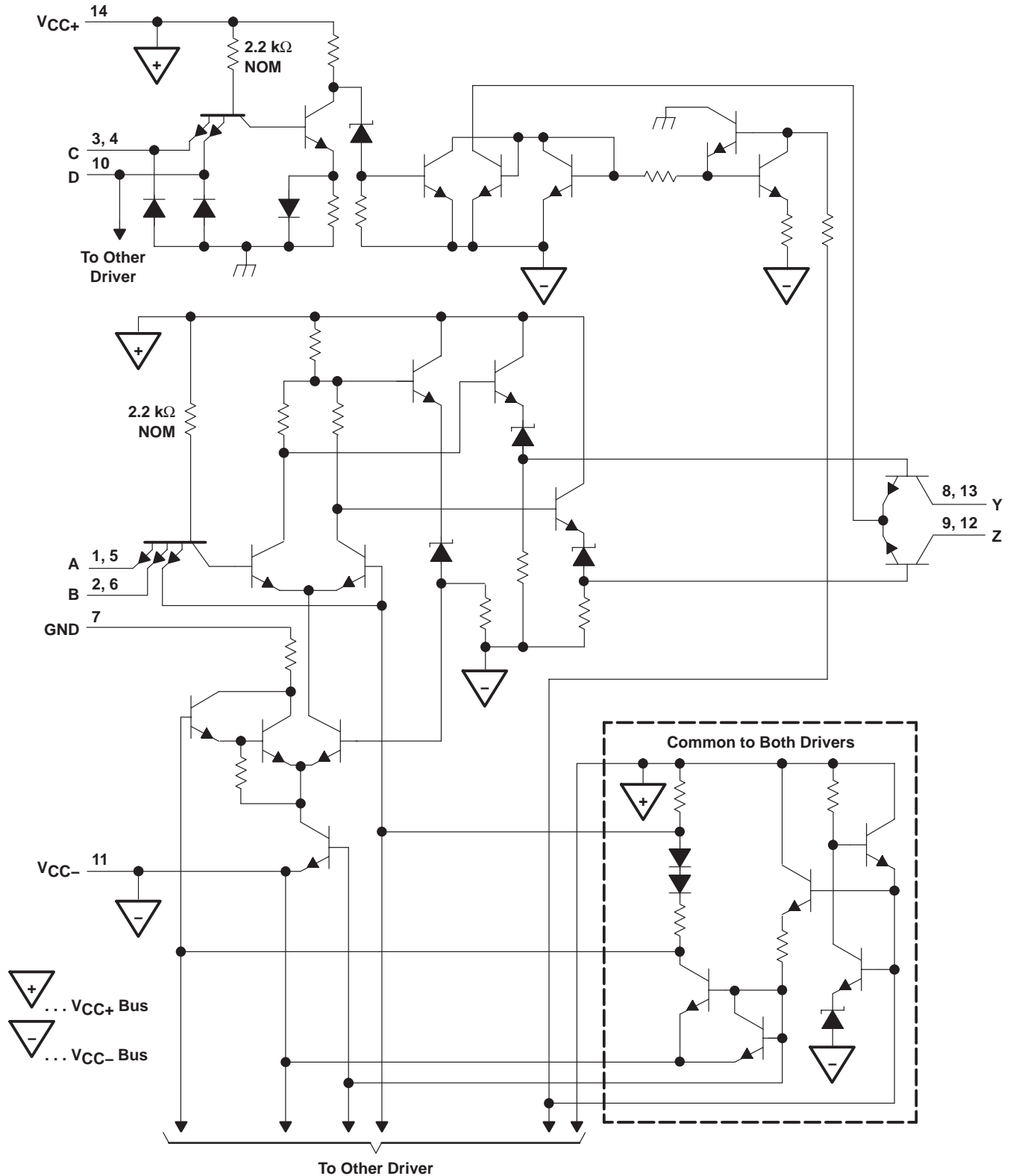
H = high level, L = low level, X = irrelevant

† When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

## schematic (each driver)



Pin numbers shown are for the D, J, N, NS, and W packages.

# SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

## absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage: $V_{CC+}$ (see Note 1)	7 V
$V_{CC-}$ (see Note 1)	-7 V
Input voltage, $V_I$	5.5 V
Output voltage range, $V_O$	-5 V to 12 V
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Package thermal impedance, $\theta_{JC}$ (see Notes 4 and 5): FK package	13.42°C/W
J package	15.05°C/W
W package	14.65°C/W
Operating virtual junction temperature	150°C
Case temperature for 60 seconds: FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J or W package	300°C
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. Voltage values are with respect to network ground terminal.
  2. Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  3. The package thermal impedance is calculated in accordance with JESD 51-7.
  4. Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JC}$ , and  $T_C$ . The maximum allowable power dissipation at any allowable case temperature is  $P_D = (T_J(\text{max}) - T_C)/\theta_{JC}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
  5. The package thermal impedance is calculated in accordance with MIL-STD-883.

## recommended operating conditions (see Note 6)

	SN55110A			SN75110A SN75112			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC+}$ Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{CC-}$ Supply voltage	-4.5	-5	-5.5	-4.75	-5	-5.25	V
Positive common-mode output voltage	0		10	0		10	V
Negative common-mode output voltage	0		-3	0		-3	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level output voltage			0.8			0.8	V
$T_A$ Operating free-air temperature	-55		125	0		70	°C

NOTE 6: When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.



# SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN55110A SN75110A			SN75112			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$	Input clamp voltage	$V_{CC\pm} = \text{MIN}$ , $I_L = -12 \text{ mA}$	-0.9	-1.5		-0.9	-1.5	V	
$I_{O(\text{on})}$	On-state output current	$V_{CC\pm} = \text{MAX}$ , $V_O = 10 \text{ V}$	12	15		27	40	mA	
		$V_{CC} = \text{MIN to MAX}$ , $V_O = -1 \text{ V to } 1 \text{ V}$ , $T_A = 25^\circ\text{C}$				24	28		32
		$V_{CC\pm} = \text{MIN}$ , $V_O = -3 \text{ V}$	6.5	12		15	27		
$I_{O(\text{off})}$	Off-state output current	$V_{CC\pm} = \text{MIN}$ , $V_O = 10 \text{ V}$			100			100	$\mu\text{A}$
$I_I$	Input current at maximum input voltage	A, B, or C inputs	$V_{CC\pm} = \text{MAX}$ , $V_I = 5.5 \text{ V}$			1			1
		D input							
$I_{IH}$	High-level input current	A, B, or C inputs	$V_{CC\pm} = \text{MAX}$ , $V_I = 2.4 \text{ V}$			40			40
		D input							
$I_{IL}$	Low-level input current	A, B, or C inputs	$V_{CC\pm} = \text{MAX}$ , $V_I = 0.4 \text{ V}$			-3			-3
		D input							
$I_{CC+(\text{on})}$	Supply current from $V_{CC}$ with driver enabled	$V_{CC\pm} = \text{MAX}$ , A and B inputs at 0.4 V, C and D inputs at 2 V	23	35		25	40	mA	
$I_{CC-(\text{on})}$	Supply current from $V_{CC-}$ with driver enabled	$V_{CC\pm} = \text{MAX}$ , A and B inputs at 0.4 V, C and D inputs at 2 V	-34	-50		-65	-100	mA	
$I_{CC+(\text{off})}$	Supply current from $V_{CC-}$ with driver inhibited	$V_{CC\pm} = \text{MAX}$ , A, B, C, and D inputs at 0.4 V	21			30		mA	
$I_{CC-(\text{off})}$	Supply current from $V_{CC\pm}$ with driver inhibited	$V_{CC\pm} = \text{MAX}$ , A, B, C, and D inputs at 0.4 V	-17			-32		mA	

† For conditions shown as MIN or MAX, use appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC+} = 5 \text{ V}$ ,  $V_{CC-} = -5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

## switching characteristics, $V_{CC\pm} = \pm 5 \text{ V}$ , $T_A = 25^\circ\text{C}$ (see Figure 1)

PARAMETERS§	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$t_{PLH}$	A or B	Y or Z	$C_L = 40 \text{ pF}$ , $R_L = 50 \Omega$ ,		9	15	ns	
$t_{PHL}$								
$t_{PLH}$	C or D	Y or Z	$C_L = 40 \text{ pF}$ , $R_L = 50 \Omega$ ,		16	25	ns	
$t_{PHL}$								

§  $t_{PLH}$  = propagation delay time, low- to high-level output

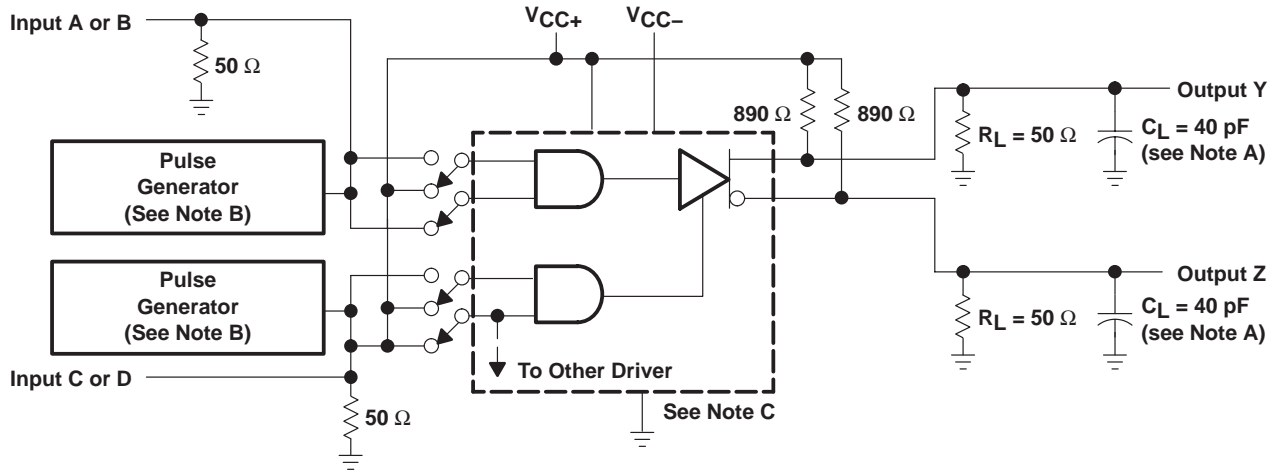
$t_{PHL}$  = propagation delay time, high- to low-level output



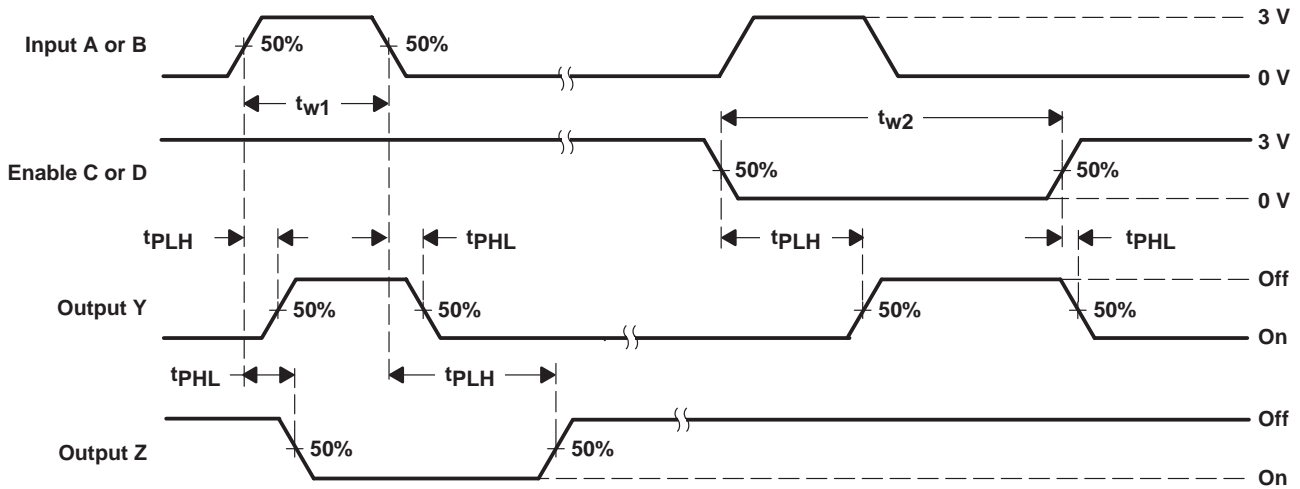
# SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

## PARAMETER MEASUREMENT INFORMATION



### TEST CIRCUIT



### VOLTAGE WAVEFORMS

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. The pulse generators have the following characteristics:  $Z_O = 50 \Omega$ ,  $t_r = t_f = 10 \pm 5 \text{ ns}$ ,  $t_{w1} = 500 \text{ ns}$ ,  $\text{PRR} \leq 1 \text{ MHz}$ ,  $t_{w2} = 1 \mu\text{s}$ ,  $\text{PRR} \leq 500 \text{ kHz}$ .  
 C. For simplicity, only one channel and the enable connections are shown.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

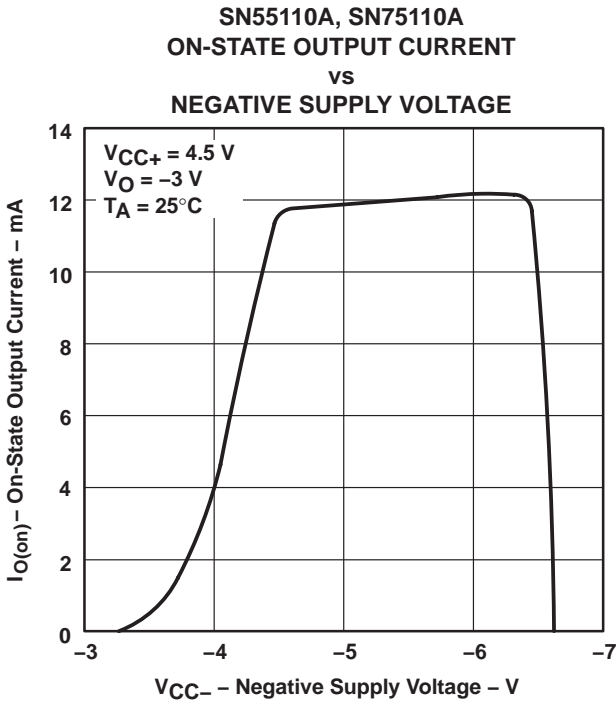


Figure 2

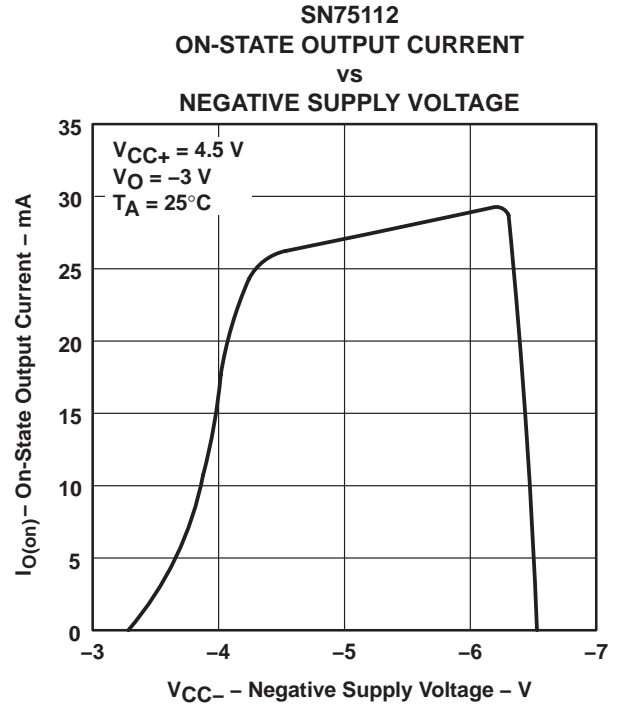


Figure 3

# SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

## APPLICATION INFORMATION

### special pulse-control circuit

Figure 4 shows a circuit that can be used as a pulse-generator output or in many other testing applications.

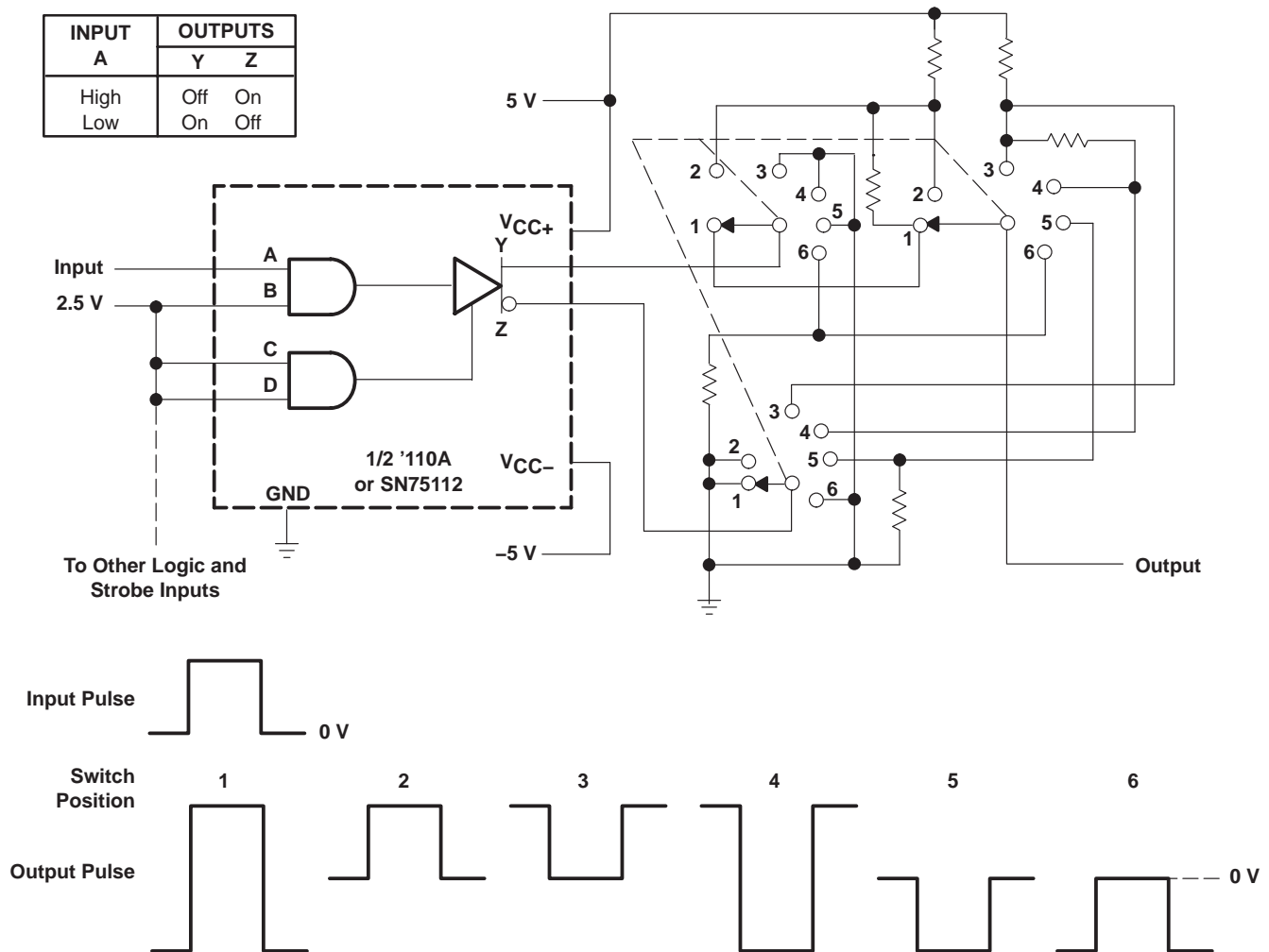


Figure 4. Pulse-Control Circuit



APPLICATION INFORMATION

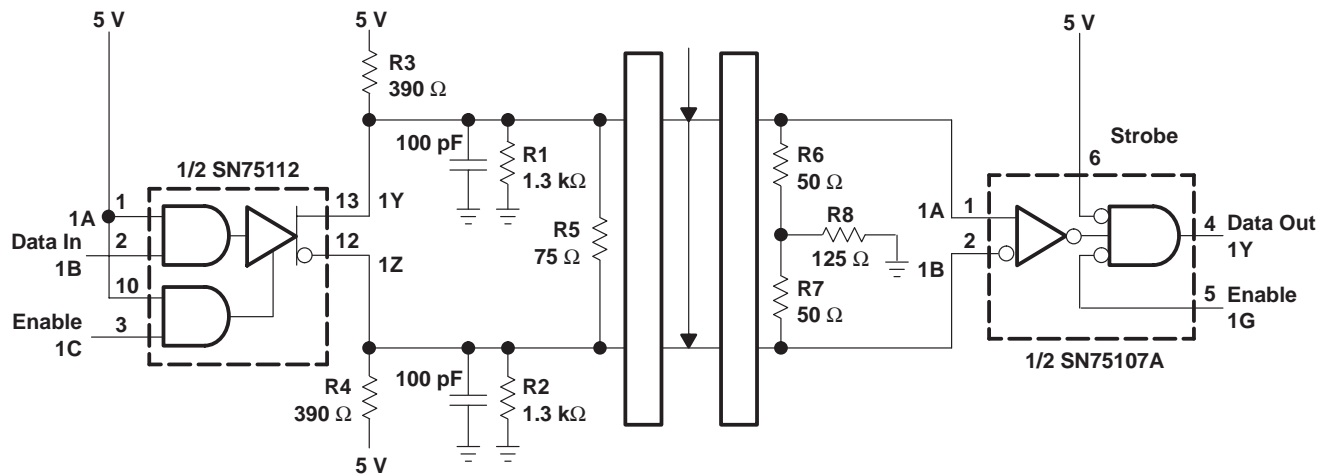
using the SN75112 as a CCITT-recommended V.35 line driver

The SN75112 dual line driver, the SN75107A dual line receiver, and some external resistors can be used to implement the data-interchange circuit of CCITT recommendation V.35 (1976) modem specification. The circuit of one channel is shown in Figure 5 and meets the requirement of the interface as specified by Appendix 11 of CCITT V.35 and is summarized in Table 1 (V.35 has been replaced by ITU V.11).

Table 1. CCITT V.35 Electrical Requirements

GENERATOR	MIN	MAX	UNIT
Source impedance, $Z_{source}$	50	150	$\Omega$
Resistance to ground, R	135	165	$\Omega$
Differential output voltage, $V_{OD}$	440	660	mV
10% to 90% rise time, $t_r$	40		ns
or	0.01 $\times$ $ui^\dagger$		
Common-mode output voltage, $V_{OC}$	-0.6	0.6	V
LOAD (RECEIVER)	MIN	MAX	UNIT
Input impedance, $Z_I$	90	110	$\Omega$
Resistance to ground, R	135	165	$\Omega$

$\dagger ui$  = unit interval or minimum signal-element pulse duration



All resistors are 5%, 1/4 W.

Figure 5. CCITT-Recommended V.35 Interface Using the SN75112 and SN75107A

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87547012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-87547012A SNJ55 110AFK	<a href="#">Samples</a>
5962-8754701CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8754701CA SNJ55110AJ	<a href="#">Samples</a>
5962-8754701DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8754701DA SNJ55110AW	<a href="#">Samples</a>
SN55110AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN55110AJ	<a href="#">Samples</a>
SN75110AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	<a href="#">Samples</a>
SN75110ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	<a href="#">Samples</a>
SN75110AN	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75110AN	<a href="#">Samples</a>
SN75110ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75110A	<a href="#">Samples</a>
SN75112D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75112	<a href="#">Samples</a>
SN75112DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75112	<a href="#">Samples</a>
SN75112N	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75112N	<a href="#">Samples</a>
SNJ55110AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962-87547012A SNJ55 110AFK	<a href="#">Samples</a>
SNJ55110AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8754701CA SNJ55110AJ	<a href="#">Samples</a>
SNJ55110AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8754701DA SNJ55110AW	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

---

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN55110A, SN75110A :**

● Catalog: [SN75110A](#)

● Military: [SN55110A](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75112DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75110ADR	SOIC	D	14	2500	333.2	345.9	28.6
SN75110ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN75110ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN75112DR	SOIC	D	14	2500	367.0	367.0	38.0

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G



J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



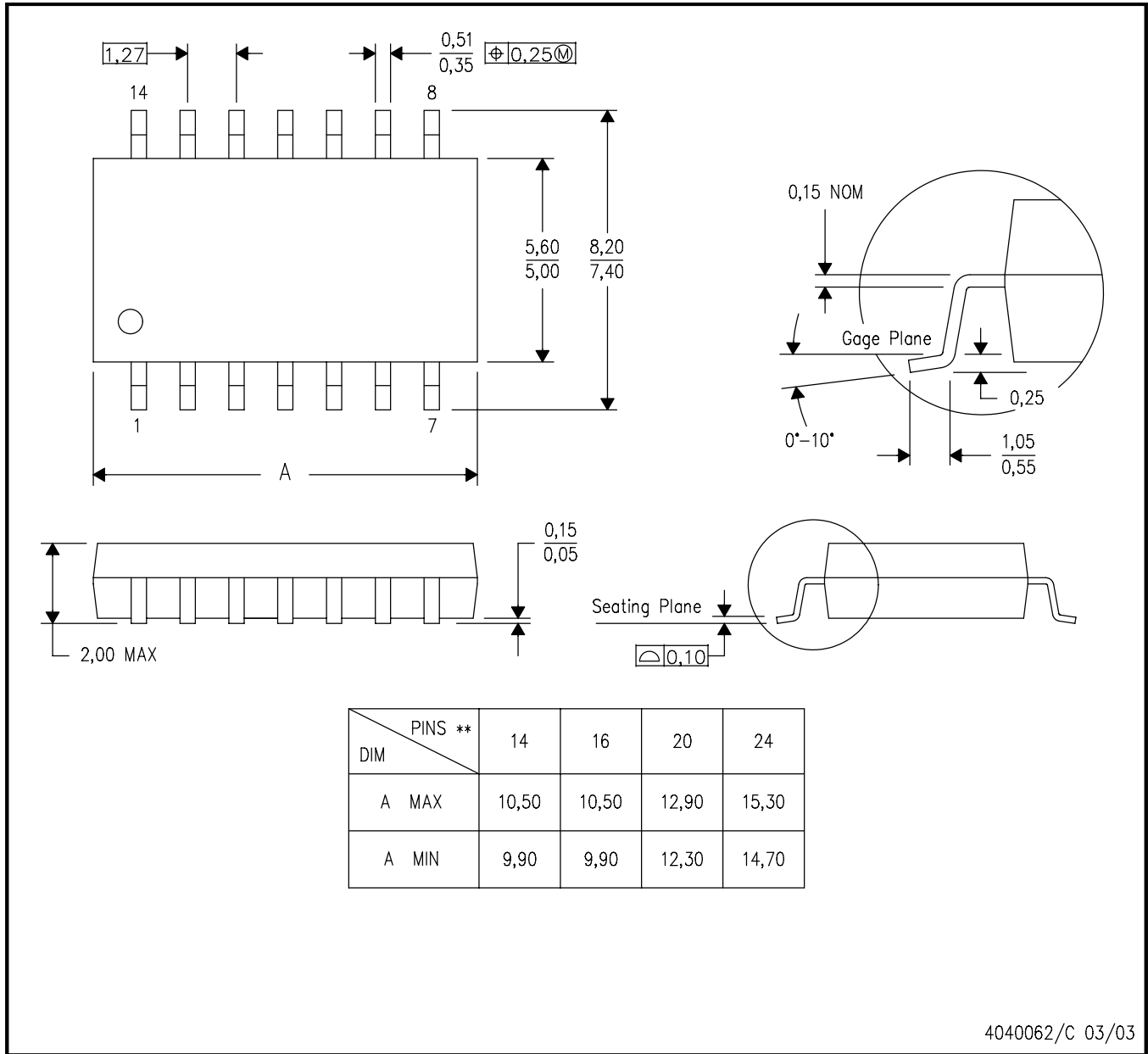
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**  
**14-PINS SHOWN**

**PLASTIC SMALL-OUTLINE PACKAGE**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.